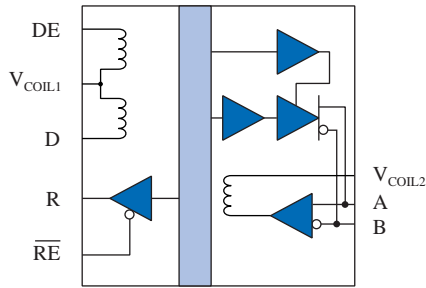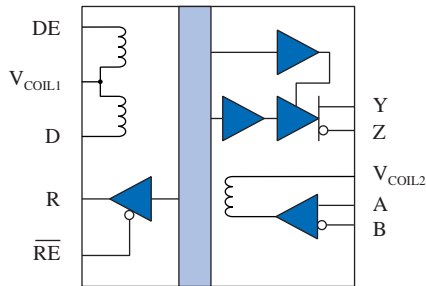# High Speed RS-485 and RS-422 Isolated Transceivers

Functional Diagrams

IL3485

IL3422

IL3485 Truth Table

$V_{(A-B)}$	DE	D	R	$\overline{RE}$	Mode
≥ 200 mV	H	H	H	L	Drive
≤ -200 mV	H	L	L	L	Drive
≥ 200 mV	L	X	H	L	Receive
≤ -200 mV	L	X	L	L	Receive
X	X	X	Z	H	X
Open	L	X	H	L	Receive

Z = High Impedance   X = Irrelevant

IL3422 Receiver

$\overline{RE}$	R	$V_{(A-B)}$
H	Z	X
L	H	≥ 200 mV
L	L	≤ -200 mV
L	H	Open

IL3422 Driver

DE	D	$V_{(Y-Z)}$
L	X	Z
H	H	≥ 200 mV
H	L	≤ -200 mV

Selection Table

Model	Full/Half Duplex	No. of Devices Allowed on Bus	Data Rate Mbps	Fail-Safe
IL3485	half	32	20	yes
IL3422	full	32	20	yes

Features

- 3.3 V / 5 V Input Supply Compatible
- 20 Mbps Data Rate
- Supports Up to 32 Nodes
- ±15 kV ESD Protection
- 2500 V_{RMS} Isolation (1 minute)
- 20 kV/µs Typical Common Mode Rejection
- Thermal Shutdown Protection
- −40°C to +85°C Temperature Range
- IEC 61010-2001 Approval
- UL1577 Approval (pending)
- 0.15" or 0.3" 16-pin SOIC Packages

Applications

- Data Loggers
- P.O.S. Systems
- Security Networks
- Building Environmental Controls
- Industrial Control Networks
- Factory Automation

Description

The IL3485 and IL3422 are galvanically isolated, differential bus transceivers designed for bidirectional data communication over balanced transmission lines. The devices use NVE's patented* IsoLoop spintronic Giant Magnetoresistance (GMR) technology. The IL3485 delivers at least 1.5 V into a 54 Ω load, and the IL3422 at least 2 V into a 100 Ω load, allowing excellent data integrity over long cables. These devices are also compatible with 3.3 V input supplies, allowing interface to standard microcontrollers without additional level shifting.

Both the IL3485 and IL3422 have current limiting and thermal shutdown features to protect against output short circuits and bus contentions that may cause excessive power dissipation. The receivers also incorporate a "fail-safe if open" design, ensuring a logic high on R if the bus lines are disconnected or "floating."

A 16 pF capacitor (C_{Boost}; see page 8) must be placed across the current limit resistor to ensure the full specified performance.

IsoLoop® is a registered trademark of NVE Corporation.
*U.S. Patent number 5,831,426; 6,300,617 and others.

REV. G

Absolute Maximum Ratings

Operating at absolute maximum ratings will not damage the device. However, extended periods of operation at the absolute maximum ratings may affect performance and reliability.

Parameters	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Storage Temperature	T_S	−65		150	°C	
Ambient Operating Temperature	T_A	−40		85	°C	
Voltage Range at A or B Bus Pins		−7		12	V	
Supply Voltage[1]	V_{DD1}, V_{DD2}	−0.5		7	V	
Digital Input Voltage		−0.5		V_{DD}+0.5	V	
Digital Output Voltage		−0.5		V_{DD}+1	V	
ESD Protection		±15			kV	
Input Current	I_{IN}	−25		+25	mA	

Note 1. All voltage values are with respect to network ground except differential I/O bus voltages.

Recommended Operating Conditions

Parameters	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Supply Voltage	V_{DD1}	3.0		5.5	V	
	V_{DD2}	4.5		5.5		
Ambient Operating Temperature	T_A	−40		85	°C	
Input Voltage at any Bus Terminal (separately or common mode)	V_I			12	V	
	V_{IC}			−7		
Input Threshold for Output Logic High	I_{INH}		1.5	0.8	mA	
Input Threshold for Output Logic Low	I_{INL}	5	3.5		mA	
Differential Input Voltage[2]	V_{ID}			+12/−7	V	
High-Level Output Current (Driver)	I_{OH}			−60	mA	
High-Level Digital Output Current (Receiver)	I_{OH}	−8		8	mA	
Low-Level Output Current (Driver)	I_{OL}	−60		60	mA	
Low-Level Digital Output Current (Receiver)	I_{OL}	−8		8	mA	
Ambient Operating Temperature	T_A	−40		85	°C	
Digital Input Signal Rise, Fall Times	t_{IR},t_{IF}			1	μs	

Insulation Specifications

Parameters	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Creepage Distance (external)		8.08			mm	
Barrier Impedance			>10^{14}‖7		Ω ‖ pF	
Leakage Current			0.2		μA	240 V_{RMS}, 60 Hz

Safety Approvals

IEC61010-2001

TUV Certificate Numbers: N1502812, N1502812-101

Classification: Reinforced Insulation

Models	Package	Pollution Degree	Material Group	Max. Working Voltage
IL3422E, IL3485E, IL3422-3E, IL3485-3E	SOIC (0.15" and 0.3")	II	III	300 V_{RMS}

UL 1577

Rated 2500 V_{RMS} for 1 minute
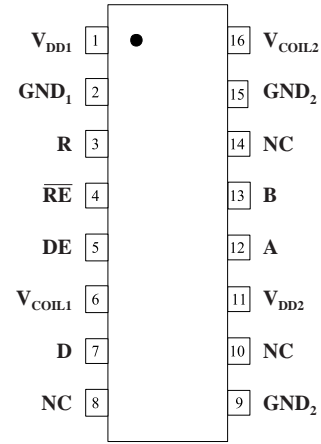Component Recognition Program File Number: E207481

Soldering Profile

Per JEDEC J-STD-020C, MSL=2

Electrostatic Discharge Sensitivity

This product has been tested for electrostatic sensitivity to the limits stated in the specifications. However, NVE recommends that all integrated circuits be handled with appropriate care to avoid damage. Damage caused by inappropriate handling or storage could range from performance degradation to complete failure.
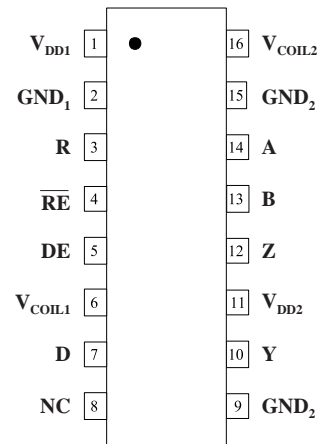
IL3485-3 Pin Connections (0.15" SOIC Package)

1	V_{DD1}	Input power supply
2	GND_1	Ground return for V_{DD1}
3	R	Output data from bus
4	$\overline{RE}$	Read enable (if RE is high, R is high impedance)
5	DE	Drive enable
6	V_{COIL1}	Coils for DE and D (connect to V_{DD1})
7	D	Data input to bus
8	NC	No internal connection
9	GND_2	Ground return for V_{DD2}
10	NC	No internal connection
11	V_{DD2}	Output power supply
12	A	Non-inverting bus line
13	B	Inverting bus line
14	NC	No internal connection
15	GND_2	Ground return for V_{DD2}
16	V_{COIL2}	Coil for R (connect to V_{DD2})

```
VDD1   1          16  VCOIL2
GND1   2          15  GND2
R      3          14  NC
RE     4          13  B
DE     5          12  A
VCOIL1 6          11  VDD2
D      7          10  NC
NC     8           9  GND2
```

IL3485-3

IL3422-3 Pin Connections (0.15" SOIC Package)

1	V_{DD1}	Input power supply
2	GND_1	Ground return for V_{DD1}
3	R	Output data from bus
4	$\overline{RE}$	Read enable (if RE is high, R is high impedance)
5	DE	Drive enable
6	V_{COIL1}	Coils for DE and D (connect to V_{DD1})
7	D	Data input to bus
8	NC	No internal connection
9	GND_2	Ground return for V_{DD2}
10	Y	Non-inverting driver bus line
11	V_{DD2}	Output power supply
12	Z	Inverting driver bus line
13	B	Inverting receiver bus line
14	A	Non-inverting receiver bus line
15	GND_2	Ground return for V_{DD2}
16	V_{COIL2}	Coil for R (connect to V_{DD2})

```
VDD1   1          16  VCOIL2
GND1   2          15  GND2
R      3          14  A
RE     4          13  B
DE     5          12  Z
VCOIL1 6          11  VDD2
D      7          10  Y
NC     8           9  GND2
```

IL3422-3

IL3485 Pin Connections (0.3" SOIC Package)

1	V_{DD1}	Input power supply
2	GND_1	Ground return for V_{DD1}
3	R	Output data from bus
4	$\overline{RE}$	Read enable (if RE is high, R is high impedance)
5	DE	Drive enable
6	V_{COIL1}	Coils for DE and D (connect to V_{DD1})
7	D	Data input to bus
8	GND_1	V_{DD1} ground return for 0.3" package (no internal connection on 0.15" IL3485-3)
9	GND_2	Ground return for V_{DD2}
10	NC	No internal connection
11	V_{DD2}	Output power supply
12	A	Non-inverting bus line
13	B	Inverting bus line
14	NC	No internal connection
15	GND_2	Ground return for V_{DD2}
16	V_{COIL2}	Coil for R (connect to V_{DD2})

V_{DD1} [1] — [16] V_{COIL2}
GND_1 [2] — [15] GND_2
R [3] — [14] NC
$\overline{RE}$ [4] — [13] B
DE [5] — [12] A
V_{COIL1} [6] — [11] V_{DD2}
D [7] — [10] NC
GND_1 [8] — [9] GND_2

IL3485

IL3422 Pin Connections (0.3" SOIC Package)

1	V_{DD1}	Input power supply
2	GND_1	Ground return for V_{DD1}
3	R	Output data from bus
4	$\overline{RE}$	Read enable (if RE is high, R is high impedance)
5	DE	Drive enable
6	V_{COIL1}	Coils for DE and D (connect to V_{DD1})
7	D	Data input to bus
8	GND_1	V_{DD1} ground return for 0.3" package (no internal connection on 0.15" IL3422-3)
9	GND_2	Ground return for V_{DD2}
10	Y	Non-inverting driver bus line
11	V_{DD2}	Output power supply
12	Z	Inverting driver bus line
13	B	Inverting receiver bus line
14	A	Non-inverting receiver bus line
15	GND_2	Ground return for V_{DD2}
16	V_{COIL2}	Coil for R (connect to V_{DD2})

V_{DD1} [1] — [16] V_{COIL2}
GND_1 [2] — [15] GND_2
R [3] — [14] A
$\overline{RE}$ [4] — [13] B
DE [5] — [12] Z
V_{COIL1} [6] — [11] V_{DD2}
D [7] — [10] Y
GND_1 [8] — [9] GND_2

IL3422

4

Driver Section

Electrical specifications are T_{min} to T_{max} unless otherwise stated.

Parameters	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Coil Input Impedance	Z_{COIL}		85‖9		Ω‖nH	$T_{AMB} = 25°C$ $V_{DD} = 3.0$ V to 5.5 V
Temperature Coefficient of Coil Resistance	TC R_{COIL}		0.2	0.25	$\Omega/°C$	$V_{DD} = 3.0$ V to 5.5 V
Output voltage				V_{DD}	V	$I_O = 0$
Differential Output Voltage	$|V_{OD1}|$			V_{DD}	V	$I_O = 0$
Differential Output Voltage	$|V_{OD2}|$	2	3		V	$R_L = 100\ \Omega$, $V_{DD} = 5$ V
Differential Output Voltage[6]	V_{OD3}	1.5	2.3		V	$R_L = 54\ \Omega$, $V_{DD} = 5$ V
Change in Magnitude[7] of Differential Output Voltage	$\Delta|V_{OD}|$			±0.2	V	$R_L = 54\ \Omega$ or $100\ \Omega$
Common Mode Output Voltage	V_{OC}			3	V	$R_L = 54\ \Omega$ or $100\ \Omega$
Change in Magnitude[7] of Common Mode Output Voltage	$\Delta|V_{OC}|$			0.2	V	$R_L = 54\ \Omega$ or $100\ \Omega$
Output Current[4]				1 −0.8	mA mA	Output disabled, $V_O = 12$ V $V_O = −7$ V
High Level Input Current	I_{IH}			0.8	mA	
Low Level Input Current	I_{IL}	5	3.5		mA	
|Short-circuit Output Current|	I_{OS}	60		250	mA	$−7$ V $< V_O <$ 12 V
Supply Current ($V_{DD2} = +5$ V) ($V_{DD1} = +5$ V)	I_{DD2} I_{DD1}		6 2.5	7 3	mA	No Load (Outputs Enabled)
Supply Current ($V_{DD1} = +3.3$ V)	I_{DD2}		1.3	2	mA	No Load (Outputs Enabled)

Switching Specifications ($V_{DD1} = +5$ V, $C_{boost} = 16pF$)						
Parameters	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Data Rate		20			Mbps	$R_L = 54\ \Omega$, $C_L = 50$ pF
Differential Output Prop Delay	$t_D(OD)$		40	65	ns	$R_L = 54\ \Omega$, $C_L = 50$ pF
Pulse Skew[10]	$t_{SK}(P)$		6	15	ns	$R_L = 54\ \Omega$, $C_L = 50$ pF
Differential Output Rise and Fall Time	$t_T(OD)$	3	12	25	ns	$R_L = 54\ \Omega$, $C_L = 50$ pF
Output Enable Time to High Level	t_{PZH}		25	40	ns	$R_L = 54\ \Omega$, $C_L = 50$ pF
Output Enable Time to Low Level	t_{PZL}		25	40	ns	$R_L = 54\ \Omega$, $C_L = 50$ pF
Output Disable Time from High Level	t_{PHZ}		25	40	ns	$R_L = 54\ \Omega$, $C_L = 50$ pF
Output Disable Time from Low Level	t_{PLZ}		25	40	ns	$R_L = 54\ \Omega$, $C_L = 50$ pF
Skew Limit[3]	$t_{SK}(LIM)$			8	ns	$R_L = 54\ \Omega$, $C_L = 50pF$
Common Mode Rejection	$|CM_H|, |CM_L|$	15	20		kV/μs	$V_T = 300\ V_{peak}$

Switching Specifications ($V_{DD1} = +3.3$ V, $C_{boost} = 16pF$)						
Parameters	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Data Rate		20			Mbps	$R_L = 54\ \Omega$, $C_L = 50$ pF
Differential Output Prop Delay	$t_D(OD)$		40	65	ns	$R_L = 54\ \Omega$, $C_L = 50$ pF
Pulse Skew[10]	$t_{SK}(P)$		6	15	ns	$R_L = 54\ \Omega$, $C_L = 50$ pF
Differential Output Rise and Fall Time	$t_T(OD)$	3	12	25	ns	$R_L = 54\ \Omega$, $C_L = 50$ pF
Output Enable Time to High Level	t_{PZH}		25	40	ns	$R_L = 54\ \Omega$, $C_L = 50$ pF
Output Enable Time to Low Level	t_{PZL}		25	40	ns	$R_L = 54\ \Omega$, $C_L = 50$ pF
Output Disable Time from High Level	t_{PHZ}		25	40	ns	$R_L = 54\ \Omega$, $C_L = 50$ pF
Output Disable Time from Low Level	t_{PLZ}		25	40	ns	$R_L = 54\ \Omega$, $C_L = 50$ pF
Skew Limit[3]	$t_{SK}(LIM)$			8	ns	$R_L = 54\ \Omega$, $C_L = 50pF$
Common Mode Rejection	$|CM_H|, |CM_L|$	15	20		kV/μs	$V_T = 300\ V_{peak}$

Receiver Section

Electrical specifications are T_{min} to T_{max} unless otherwise stated.

Parameters	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Coil Input Impedance	Z_{COIL}		85‖9		Ω‖nH	$T_{AMB} = 25°C$ $V_{DD} = 3.0$ V to 5.5 V
Temperature Coefficient of Coil Resistance	TC R_{COIL}		0.2	0.25	Ω/°C	$V_{DD} = 3.0$ V to 5.5 V
Positive-going Input Threshold	V_{IT+}			0.2	V	-7 V $< V_{CM} < 12$ V
Negative-going Input Threshold	V_{IT-}	-0.2			V	-7 V $< V_{CM} < 12$ V
Hysteresis Voltage ($V_{it+} - V_{it-}$)	V_{HYS}		70		mV	$V_{CM} = 0$V, T = 25°C
High Level Digital Output Voltage	V_{OH}	$V_{DD} - 0.2$	$V_{DD} - 0.2$		V	$V_{ID} = 200$ mV
						$I_{OH} = 4$ mA
Low Level Digital Output Voltage	V_{OL}			0.8	V	$V_{ID} = -200$ mV
						$I_{OL} = 4$ mA
High impedance state output current	I_{OZ}			10	µA	$0.4 \leq V_O \leq (V_{DD2} - 0.5)$ V
Line Input Current[8]	I_I			1	mA	$V_I = 12$ V
				-0.8		$V_I = -7$ V
Input Resistance	r_I	12	25		kΩ	
Switching Characteristics. ($V_{DD1} = +5$ V, $C_{boost} = 16$pF)						
Parameters	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Data Rate		20			Mbps	$R_L = 54$ Ω, $C_L = 50$ pF
Propagation Delay[9]	t_{PD}		50	85	ns	$-1.5 \leq V_O \leq 1.5$ V, $C_L = 15$ pF
Pulse Skew[10]	$t_{SK}(P)$		10	17	ns	$-1.5 \leq V_O \leq 1.5$ V, $C_L = 15$ pF
Skew Limit[3]	$t_{SK}(LIM)$		2	8	ns	$R_L = 54$ Ω, $C_L = 50$ pF
Output Enable Time to High Level	t_{PZH}		4	10	ns	$C_L = 15$ pF
Output Enable Time to Low Level	t_{PZL}		4	10	ns	$C_L = 15$ pF
Output Disable Time from High Level	t_{PHZ}		4	10	ns	$C_L = 15$ pF
Output Disable Time from Low Level	t_{PLZ}		4	10	ns	$C_L = 15$ pF
Switching Characteristics. ($V_{DD1} = +3.3$ V, $C_{boost} = 16$pF)						
Parameters	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Data Rate		20			Mbps	$R_L = 54$ Ω, $C_L = 50$ pF
Propagation Delay[9]	t_{PD}		55	85	ns	$-1.5 \leq V_O \leq 1.5$ V, $C_L = 15$ pF
Pulse Skew[10]	$t_{SK}(P)$		12	18	ns	$-1.5 \leq V_O \leq 1.5$ V, $C_L = 15$ pF
Skew Limit[3]	$t_{SK}(LIM)$		4	10	ns	$R_L = 54$ Ω, $C_L = 50$ pF
Output Enable Time to High Level	t_{PZH}		5	10	ns	$C_L = 15$ pF
Output Enable Time to Low Level	t_{PZL}		5	10	ns	$C_L = 15$ pF
Output Disable Time from High Level	t_{PHZ}		5	10	ns	$C_L = 15$ pF
Output Disable Time from Low Level	t_{PLZ}		5	10	ns	$C_L = 15$ pF

Notes (apply to both driver and receiver sections):

1. All voltages are with respect to network ground except differential I/O bus voltages.
2. Differential input/output voltage is measured at the non-inverting terminal A with respect to the inverting terminal B.
3. Skew limit is the maximum difference in any two channels in one device.
4. The power-off measurement in ANSI Standard EIA/TIA-422-B applies to disabled outputs only and is not applied to combined inputs and outputs.
5. All typical values are at V_{DD1}, $V_{DD2} = 5$ V or $V_{DD1} = 3.3$ V and $T_A = 25°C$.
6. While -7 V $< V_{CM} < 12$ V, the minimum V_{OD2} with a 54 Ω load is either ½ V_{OD1} or 1.5 V, whichever is greater.
7. $\Delta|VOD|$ and $\Delta|VOC|$ are the changes in magnitude of V_{OD} and V_{OC}, respectively, that occur when the input is changed from one logic state to the other.
8. This applies for both power on and power off; refer to ANSI standard RS-485 for exact condition. The EIA/TIA-422-B limit does not apply for a combined driver and receiver terminal.
9. Includes 10 ns read enable time. Maximum propagation delay is 25 ns after read assertion.
10. Pulse skew is defined as the $|t_{PLH} - t_{PHL}|$ of each channel.

Power Supply Decoupling

Both V_{DD1} and V_{DD2} must be bypassed with 47 nF ceramic capacitors. These should be placed as close as possible to V_{DD} pins for proper operation. Additionally, V_{DD2} should be bypassed with a 10 µF tantalum capacitor.

Operation

The IL3422 and IL3485 are current-mode devices. Changes in input coil current switch internal spintronic GMR sensors, which then change the logic state of the outputs. The GMR bridge is designed so the output of the isolator is logic high when no field signal is present.

A single resistor is required to limit the input coil current to the recommended 5 mA. The absolute maximum current through any coil is 25 mA DC. Although logic threshold currents are typically less than the worst-case 5 mA, NVE recommends designing for 5 mA logic threshold current in all applications.

Figure 1 shows the input response of the IL3422 and IL3485. Output logic high is the zero input current state. The output switches to the low state with approximately 3.5 mA of coil current, and back to the high state when the input current falls below approximately 1.5 mA. This allows glitch-free interface with low slew-rate signals.
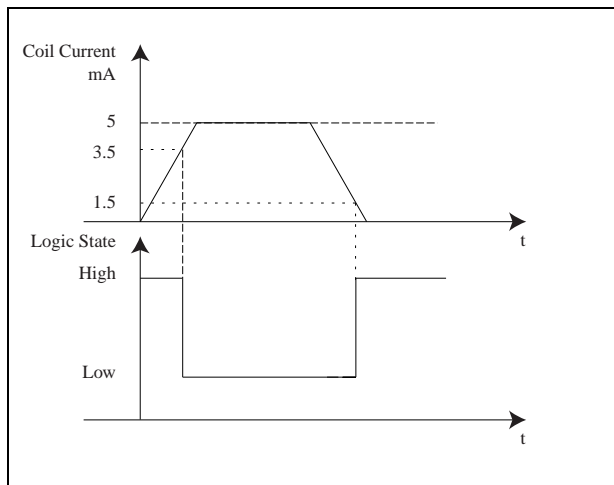
Figure 1. IL3000 Series Input Transfer Function

Magnetic Field Booster Capacitor

A small capacitor (200 pF to 1 nF) in parallel the current limiting resistor boosts the instantaneous current through the coil at the point of signal transition. The resultant magnetic field boost pushes the GMR bridge output through the comparator threshold voltage with less propagation delay and pulse width distortion. The booster capacitor gives a great deal of design headroom and can usually eliminate design concerns related to temperature and power supply fluctuations.
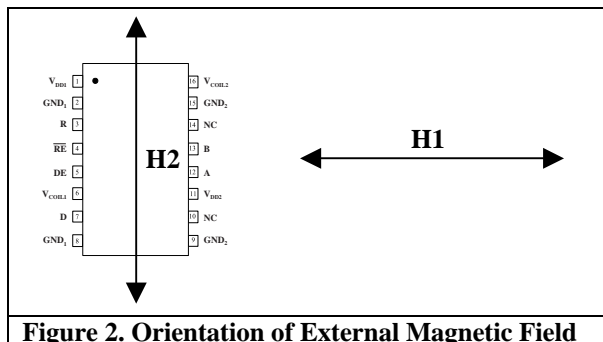
Magnetic Field Immunity

IsoLoop devices operate by imposing a magnetic field on a GMR sensor, which translates the change in field into a change in logic state. The devices are manufactured with a magnetic shield above the sensor. The shield acts as a flux concentrator to boost the magnetic signal from the internal coil, and as a shield against external magnetic fields. The shield absorbs surrounding stray flux until it becomes saturated. At saturation the shield is transparent to external applied fields, and the GMR sensor may react to the field. To compensate for this effect, IsoLoop Isolators use Wheatstone Bridge structures that are only sensitive to differential magnetic fields. There are several ways to further enhanced the magnetic field immunity of IL3000 Transceivers. Providing a larger internal field will reduce the effect of an external field on the GMR sensor. Immunity to external magnetic fields can also be enhanced by proper orientation of the device with respect to the field direction and field boosting capacitors.

Orientation of the device with respect to the field direction

An applied field in the "H1" direction is the worst case for magnetic immunity. In this case the external field is in the same direction as the applied internal field. In one direction it will tend to help switching; in the other it will hinder switching. This can cause unpredictable operation.

An applied field in the direction of "H2" has considerably less effect on the sensor and will result in significantly higher immunity levels as shown in Table 1.

The greatest magnetic immunity is achieved by adding the current boost capacitor across the input resistor. Very high immunity can be achieved with this method.

Figure 2. Orientation of External Magnetic Field

Method	Approximate Immunity	Immunity Description
Field applied in direction H1	±20 Gauss	A DC current of 16 A flowing in a conductor 1 cm from the device could cause disturbance
Field applied in direction H2	±70 Gauss	A DC current of 56 A flowing in a conductor 1 cm from the device could cause disturbance
Field applied in any direction but with field booster capacitor (1 nF) in circuit	±250 Gauss	A DC current of 200 A flowing in a conductor 1 cm from the device could cause disturbance
Table 1. Magnetic Immunity		

Data Rate and Magnetic Field Immunity

It is easier to disrupt an isolated DC signal with an external magnetic field than it is to disrupt an isolated AC signal. Similarly, a DC magnetic field will have a greater effect on the device than an AC magnetic field of the same effective magnitude. For example, signals with pulses greater than 100 μs long are more susceptible to magnetic fields than shorter pulse widths. For input signals faster than 1 MHz, a 1 nF field boost capacitor provides as much as 400 Gauss immunity, while the same input capacitor might provide just 70 Gauss of immunity at 50 kHz.

Applications Information

RS-485 and RS-422 are differential (balanced) data transmission standards for use over long distances or in noisy environments. RS-422 is an RS-485 subset, so RS-485 transceivers are also RS-422-compliant. RS-422 is a multi-drop standard allowing only one driver and up to 10 receivers on each bus (assuming unit load receivers). RS-485 is a true multipoint standard which allows up to 32 unit load devices (any combination of drivers and receivers) on each bus. To allow for multipoint operation, RS-485 requires drivers to handle bus contention without damage. Another important advantage of RS-485 is the extended common-mode range (CMR), which requires driver outputs and receiver inputs withstand +12 V to −7 V. RS-422 and RS-485 are intended for runs as long as 4,000 feet (1,200 m), so the wide CMR is necessary for ground potential differences, as well as voltages induced in the cable by external fields.

Receiver Features

IL3000 transceivers have differential input receivers for maximum noise immunity and common-mode rejection. Input sensitivity is ±200 mV as required by the RS-422 and RS-485 specifications. The receivers include a "fail-safe if open" function that guarantees a high level receiver output if the receiver inputs are unconnected (floating). Receivers easily meet the data rates supported by the corresponding driver. IL3000-Series receiver outputs have tri-state capabilities with active low RE inputs.

Driver Features

The RS485/422 driver is a differential output device that delivers at least 1.5 V across a 54 Ω load (RS-485), and at least 2 V across a 100 Ω load (RS-422). The driver features low propagation delay skew to maximize bit width and minimize EMI. IL3222 and IL3285 drivers have tri-state capability with an active high DE input.

Cabling, Data Rate and Terminations

Cabling:

Use twisted-pair cable. The cable can be unshielded if it is short (<10 m) and the data rate is slow (<100 Kbps). Otherwise, use screened cable with the shield tied to earth ground at one end only. Do not tie the shield to digital ground. The other end of the shield may be tied to earth ground through an RC network. This prevents a DC ground loop in the shield. Shielded cable minimizes EMI emissions and external noise coupling to the bus.
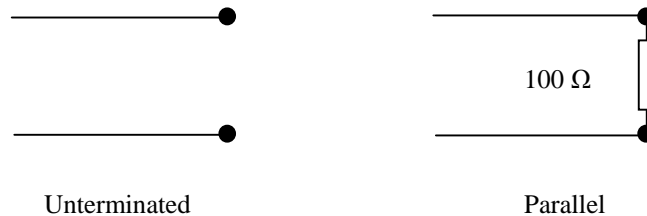
Data Rate:

The longer the cable, the slower the data rate. The RS-485 bus can transmit ground over 4,000 feet (1,200 m) or at 10Mbps, but not both at the same time. Transducer and cable characteristics combine to act as a filter with the general response shown in Figure 3. Other parameters such as acceptable jitter affect the final cable length versus data rate tradeoff. Less jitter means better signal quality but shorter cable lengths or slower data rates. Figure 3 shows a generally accepted 30% jitter and a corresponding data rate versus cable length.

Figure 3. Cable Length vs. Data Rate (30% jitter).
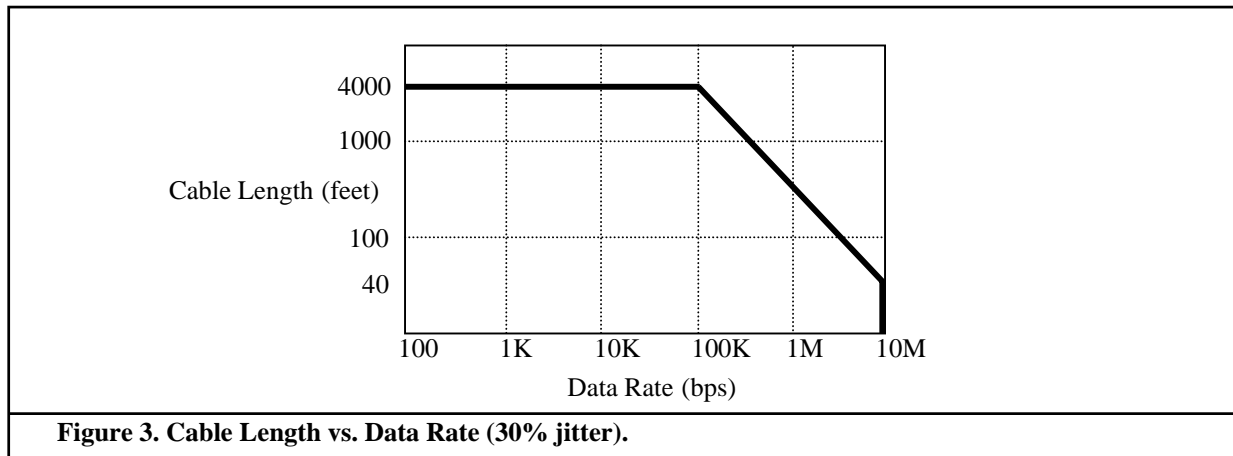
Terminations:

Transmission lines should be terminated to avoid reflections that cause data errors. In RS-485 systems both ends of the bus, not every node, should be terminated. In RS-422 systems only the receiver end should be terminated.

Unterminated   Parallel

Proper termination is imperative when using IL3485 and IL3422 to minimize reflections. Unterminated lines are only suitable for very low data rates and very short cable runs, otherwise line reflections cause problems. Parallel terminations are the most popular. They allow high data rates and excellent signal quality.

Occasionally in noisy environments, fast pulses or noise appearing on the bus lines cause errors. One way of alleviating such errors without adding circuit delays is to place a series resistor in the bus line. Depending on the power supply, the resistor should be between 300 Ω (3 V supply) and 500 Ω (5 V supply).

Typical Coil Connections

| $V_{DD1} = V_{DD2} = 5$ V | R1, R2, R3 = 931 Ω |
| $V_{DD1} = 3.3$ V | R1, R2 = 590 Ω; R3 = 931 Ω |

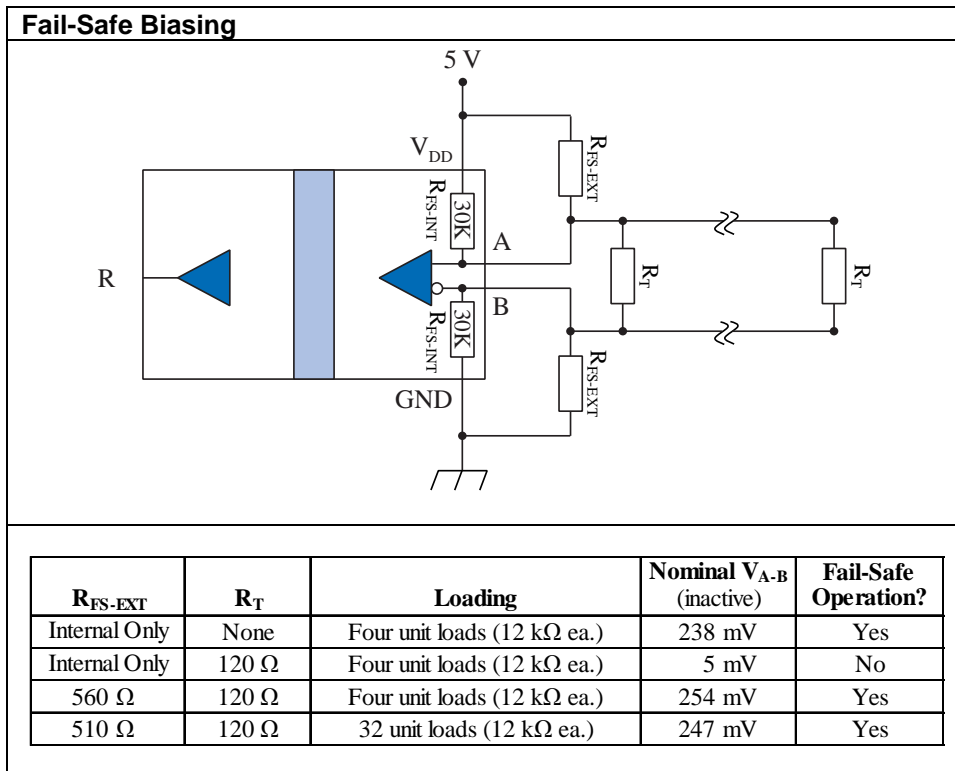| $V_{DD1} = V_{DD2} = 5$ V | R1, R2, R3 = 931 Ω |
| $V_{DD1} = 3.3$ V | R1, R2 = 590 Ω; R3 = 931 Ω |

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Fail-Safe Operation:

"Fail-safe operation" is defined here as the forcing of a logic high state on the "R" output in response to an open-circuit condition between the "A" and "B" lines of the bus, or when no drivers are active on the bus.

Proper biasing can ensure fail-safe operation, that is a known state when there are no active drivers on the bus. IL3000-Series Isolated Transceivers include internal pull-up and pull-down resistors of approximately 30 kΩ in the receiver section (R_{FS-INT}; see figure below). These internal resistors are designed to ensure failsafe operation but only if there are no termination resistors. The entire V_{DD} will appear between inputs "A" and "B" if there is no loading and no termination resistors, and there will be more than the required 200 mV with up to four RS-485/RS-422 worst-case Unit Loads of 12 kΩ. Many designs operating below 1 Mbps or less than 1,000 feet are unterminated. Termination resistors may not be necessary for very low data rates and very short cable runs because reflections have time to settle before data sampling, which occurs at the middle of the bit interval.

In busses with low-impedance termination resistors, however, the differential voltage across the conductor pair will be close to zero with no active drivers. In this case the state of the bus is indeterminate, and the idle bus will be susceptible to noise. For example, with 120 Ω termination resistors (R_T) on each end of the cable, and four Unit Loads (12 kΩ each), without external fail-safe biasing resistors the internal pull-up and pull-down resistors will produce a voltage between inputs "A" and "B" of only about 5 mV. This is not nearly enough to ensure a known state. External fail-safe biasing resistors (R_{FS-EXT}) at one end of the bus can ensure fail-safe operation with a terminated bus. Resistors should be selected so that under worst-case power supply and resistor tolerances there is at least 200 mV across the conductor pair with no active drivers to meet the input sensitivity specification of the RS-422 and RS-485 standards.
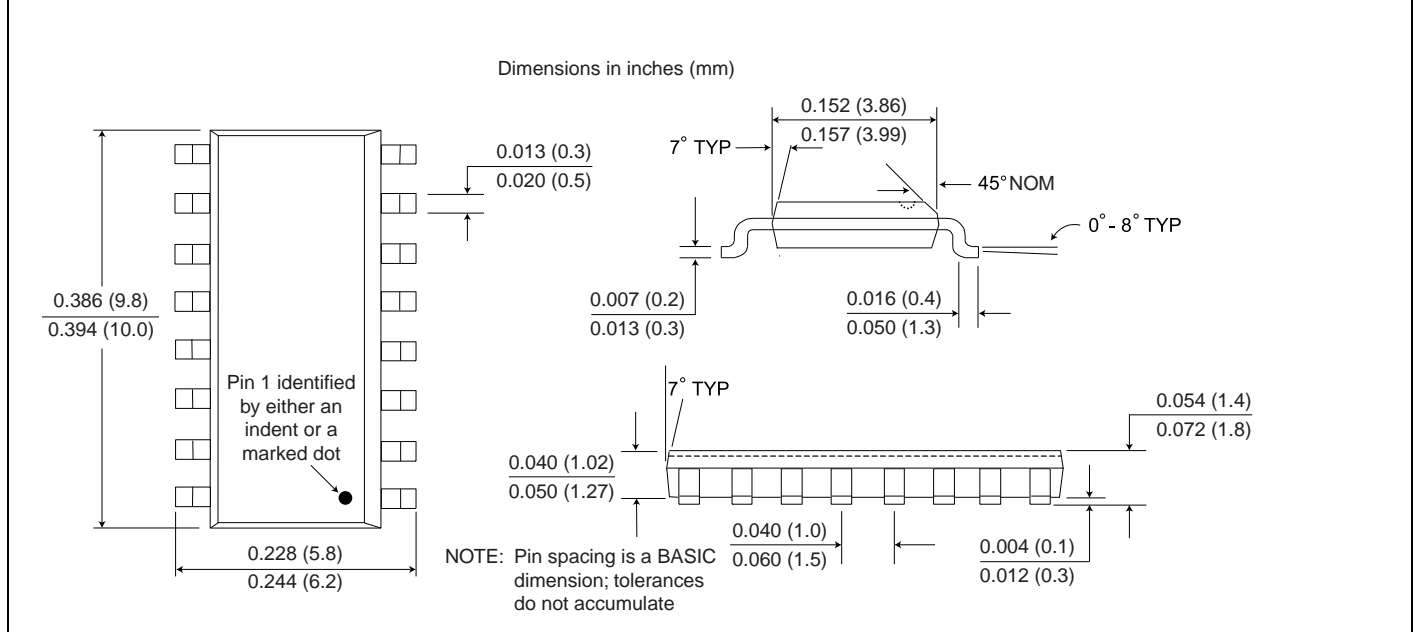
Using the same value for pull-up and pull-down biasing resistors maintains balance for positive- and negative going transitions. Lower-value resistors increase inactive noise immunity at the expense of quiescent power consumption. Note that each Unit Load on the bus adds a worst-case loading of 12 kΩ across the conductor pair, and 32 Unit Loads add 375 Ω worst-case loading. The more loads on the bus, the lower the required values of the biasing resistors.

In the example with two 120 Ω termination resistors and four Unit Loads, 560 Ω external biasing resistors provide more than 200 mV between "A" and "B" with adequate margin for power supply variations and resistor tolerances. This ensures a known state when there are no active drivers. Other illustrative examples are shown in the table below.

Fail-Safe Biasing

R_{FS-EXT}	R_T	Loading	Nominal V_{A-B} (inactive)	Fail-Safe Operation?
Internal Only	None	Four unit loads (12 kΩ ea.)	238 mV	Yes
Internal Only	120 Ω	Four unit loads (12 kΩ ea.)	5 mV	No
560 Ω	120 Ω	Four unit loads (12 kΩ ea.)	254 mV	Yes
510 Ω	120 Ω	32 unit loads (12 kΩ ea.)	247 mV	Yes

Package Drawings, Dimensions and Specifications

0.15" 16-pin SOIC Package

Dimensions in inches (mm)

0.013 (0.3)
0.020 (0.5)

0.152 (3.86)
0.157 (3.99)

7° TYP

45° NOM

0° - 8° TYP

0.386 (9.8)
0.394 (10.0)

0.007 (0.2)
0.013 (0.3)

0.016 (0.4)
0.050 (1.3)

Pin 1 identified by either an indent or a marked dot

7° TYP

0.054 (1.4)
0.072 (1.8)

0.040 (1.02)
0.050 (1.27)

0.228 (5.8)
0.244 (6.2)

0.040 (1.0)
0.060 (1.5)

0.004 (0.1)
0.012 (0.3)

NOTE: Pin spacing is a BASIC dimension; tolerances do not accumulate

0.3" 16-pin SOIC Package

Dimensions in inches (mm)

0.013 (0.3)
0.020 (0.5)

0.287 (7.29)
0.300 (7.62)

7° TYP

45° NOM

0° - 8° TYP

0.397 (10.1)
0.413 (10.5)

0.007 (0.2)
0.013 (0.3)

0.016 (0.4)
0.050 (1.3)

Pin 1 identified by either an indent or a marked dot

7° TYP

0.092 (2.34)
0.105 (2.67)

0.08 (2.0)
0.10 (2.5)

0.394 (10.00)
0.419 (10.64)

0.040 (1.0)
0.060 (1.5)

0.004 (0.1)
0.012 (0.3)

NOTE: Pin spacing is a BASIC dimension; tolerances do not accumulate

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Ordering Information and Valid Part Numbers

IL 3485 -3 E TR13

Bulk Packaging
Blank = Tube
TR13 = 13" Tape and Reel

Package
    E = RoHS Compliant

Package Type
Blank = 0.3" SOIC
    -3 = 0.15" SOIC

Base Part Number
    3485 = RS-485 Transceiver
    3422 = RS-422 Transmitter/Receiver

Product Family
    IL = Isolators
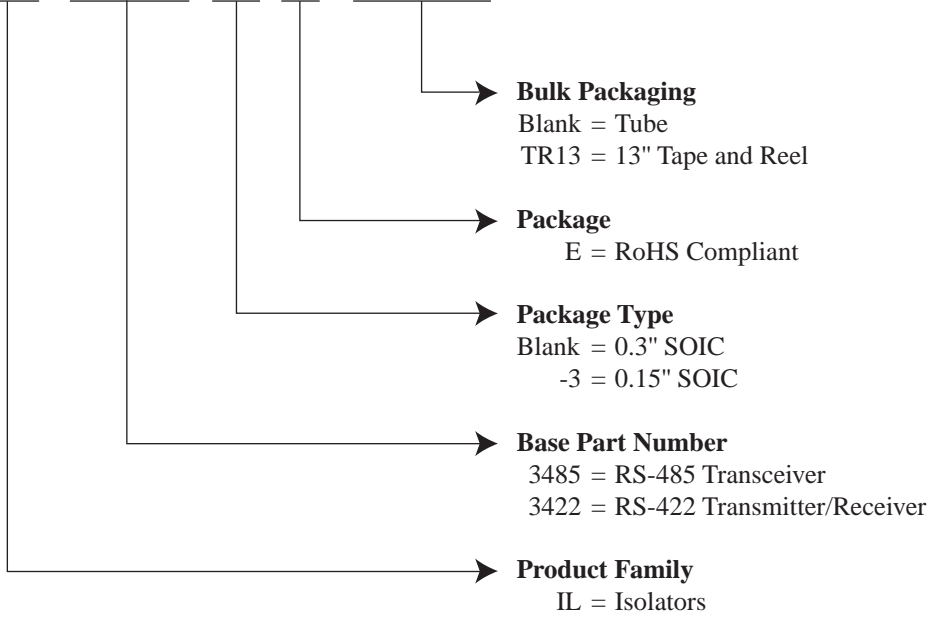
Valid Part Numbers

IL3485E
IL3485E TR13
IL3485-3E
IL3485-3E TR13

IL3422E
IL3422E TR13
IL3422-3E
IL3422-3E TR13

RoHS
COMPLIANT

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Revision History

ISB-DS-001-IL3485/22-G
February 2008

Changes
- Added typical coil resistance and temperature coefficient specifications.
- Added note on package drawings that pin-spacing tolerances are non-accumulating.

ISB-DS-001-IL3485/22-F

Changes
- Changed ordering information to reflect that devices are now fully RoHS compliant with no exemptions.

ISB-DS-001-IL3485/22-E

Changes
- Eliminated soldering profile chart

ISB-DS-001-IL3485/22-D

Changes
- Separate pinout diagrams for narrow- and wide-body packages

ISB-DS-001-IL3485/22-C

Changes
- Added "Open" input condition to truth tables
- Fail-safe biasing section added
- Narrow-body-SOIC packages added

ISB-DS-001-IL3485/22-B

Changes
1. Capacitor Information added on page 1
2. Input Signal Rise/Fall times changed from 10 μs to 1μs
3. Typical coil formations show C_{Boost}
4. Switching characteristics show $C_{Boost} = 16$ pF

ISB-DS-001-IL3485/22-A

Initial Release

About NVE

An ISO 9001 Certified Company

NVE Corporation manufactures innovative products based on unique spintronic Giant Magnetoresistive (GMR) technology. Products include Magnetic Field Sensors, Magnetic Field Gradient Sensors (Gradiometers), Digital Magnetic Field Sensors, Digital Signal Isolators, and Isolated Bus Transceivers.

NVE pioneered spintronics and in 1994 introduced the world's first products using GMR material, a line of ultra-precise magnetic sensors for position, magnetic media, gear speed and current sensing.

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Specifications are subject to change without notice.

ISB-DS-001-IL3485/22-G
February 2008